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Snubberless™, logic level and standard 8 A Triacs

Datasheet - production data

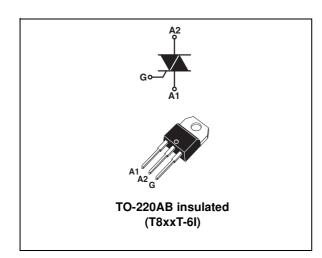


Table 1. Device summary

Part number	Symbol	Value		
T810T-6I	I _{GT} 3Q logic level	10 mA		
T820T-6I T835T-6I	I _{GT} 3Q Snubberless	20 / 35 mA		
T825T-6I	I _{GT} 4Q standard	25 mA		

Features

- Medium current Triac
- High static and dynamic commutation
- · Low thermal resistance with clip bonding
- Packages is RoHS (2002/95/EC) compliant
- 600 V V_{RM}
- UL certified (ref. file E81734)

Applications

- Value sensitive application
- General purpose ac line load switching
- Motor control circuits in power tools
- Small home appliances, lighting
- Inrush current limiting circuits
- Overvoltage crowbar protection

Description

Available in through-hole, the T8T series of Triacs can be used as on/off or phase angle control function in general purpose ac switching where high commutation capability is required.

This series can be designed in many value sensitive appliances thanks to the parameters guidance provided in the following pages.

Provides insulation rated at 2500 V rms (TO-220AB insulated package).

TM: Snubberless is a trademark of STMicroelectronics

Characteristics T8T

1 Characteristics

Table 2. Absolute ratings (limiting values; T_j = 25 °C, unless otherwise specified)

Symbol	Parameter			Value	Unit
I _{T(RMS)}	On-state rms current (full sine wave) $T_c = 97 ^{\circ}\text{C}$		T _c = 97 °C	8	Α
1.	Non repetitive surge peak on-state current	F = 50 Hz	t _p = 20 ms	60	Α
I _{TSM}	(full cycle, T _j initial = 25 °C)	F = 60 Hz	$t_p = 16.7 \text{ ms}$	63	A
l ² t	I ² t Value for fusing t _p :			26	A ² s
dI/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$ $t_r \le 100 \text{ ns}$ $F = 60 \text{ Hz}$		T _j = 125 °C	50	A/μs
V _{DSM} , V _{RSM}	Non repetitive surge peak off-state voltage $t_p = 10 \text{ ms}$		T _j = 25 °C	V _{DRM} , V _{RRM} + 100	V
I _{GM}	Peak gate current $t_p = 20 \ \mu s$ $T_j = 125 \ ^{\circ}C$		T _j = 125 °C	4	Α
P _{G(AV)}	Average gate power dissipation $T_j = 125 ^{\circ}\text{C}$			1	W
T _{stg}	Storage junction temperature range			- 40 to + 150	°C
Tj	Operating junction temperature range			- 40 to + 125	°C



T8T Characteristics

Table 3. Electrical characteristics (T_j = 25 °C, unless otherwise specified)

Cymhal	Toot conditions	Ouedrant		Т8ххТ			11	
Symbol	Test conditions	Quadrant		T810T	T820T	T825T	T835T	Unit
I _{GT} ⁽¹⁾	$V_D = 12 \text{ V}, R_L = 30 \Omega$	I - II - III	MAX.	10	20	25	35	mA
'GT`		IV				40		
V _{GT}	$V_D = V_{DRM}, R_L = 30 \Omega,$ $T_j = 25 ^{\circ}C$	ALL	MAX.		1	.3		V
V _{GD}	$V_D = V_{DRM}, R_L = 3.3 \text{ k}\Omega,$ $T_j = 125 \text{ °C}$	ALL	MIN.	0.2		V		
I _H ⁽²⁾	I _T = 500 mA		MAX.	15	25	30	40	mA
	I _G = 1.2 I _{GT}	1 - 111	MAX.	20	35	40	50	mA
IL		IV				40		
		II		25	40	70	70	
dV/dt (2)	V 679/ V gata anan	T _j = 125 °C	MIN.	100	750	500	2000	V/μs
u v/ui v	$V_D = 67\% V_{DRM,}$ gate open	$T_j = 150 {}^{\circ}C^{(3)}$		50	500	300	1000	
	$(dV/dt)c = 0.1 V/\mu s$			5.4				
	$(dV/dt)c = 10 V/\mu s$	T _j = 125 °C		2		4.5		
(dI/dt)c (2)	Without snubber		N A I N I		3.4		8	A /m c
	$(dV/dt)c = 0.1 V/\mu s$		MIN.	2.5				A/ms
	$(dV/dt)c = 10 V/\mu s$	$T_j = 150 {}^{\circ}C^{(3)}$		1		2		
	Without snubber				2		6.5	

^{1.} Minimum $I_{\mbox{\footnotesize GT}}$ is guaranteed at 5% of $I_{\mbox{\footnotesize GT}}$ max.

Table 4. Static characteristics

Symbol	Test conditions				Unit
V _T ⁽¹⁾	$I_{TM} = 11.3 \text{ A}, t_p = 380 \mu\text{s}$	T _j = 25 °C	MAX.	1.60	V
V _{TO} (1)	Threshold voltage	T _j = 125 °C	MAX.	0.87	V
R _D ⁽¹⁾	Dynamic resistance	T _j = 125 °C	MAX.	60	mΩ
	VV	T _j = 25 °C	MAX.	5	μΑ
I _{DRM} ,	$V_{DRM} = V_{RRM}$	T _j = 125 °C		1	m A
IRRM	$V_D = 0.9 \times V_{DRM}$	$T_j = 150 {}^{\circ}C^{(2)}$	TYP.	1.9	mA

^{1.} For both polarities of A2 referenced to A1.

^{2.} For both polarities of A2 referenced to A1.

^{3.} Derating information for excess temperature above $T_{j}\,\text{max}.$

^{2.} Derating information for excess temperature above $\boldsymbol{T}_{j}\,\text{max}.$

Characteristics T8T

Table 5. Thermal resistance

Symbol	Parameter	Value	Unit
R _{th(j-c)}	Junction to case (AC)	2.8	°C/W
R _{th(j-a)}	Junction to ambient (DC)	60	°C/W

Figure 1. Maximum power dissipation versus rms on-state current

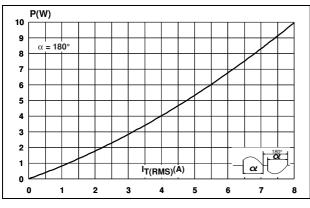


Figure 2. On-state rms current versus case temperature

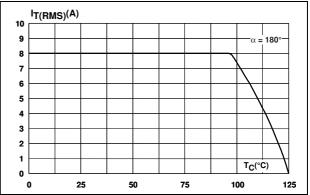
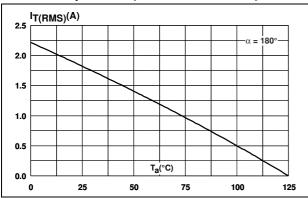


Figure 3. On-state rms current versus ambient temperature (free air convection)

Figure 4. Relative variation of thermal impedance versus pulse duration

- ...K = [Z_{th} / R_{th}]



1.0E-01

1.0E-02

1.0E-03

1.0E-02

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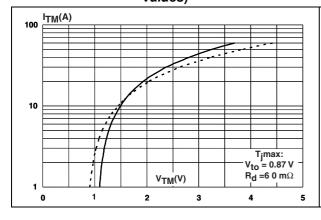
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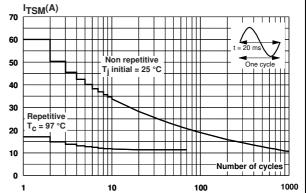
1.0E-03

1.0E-03

Figure 5. On-state characteristics (maximum values)

Figure 6. Surge peak on state current versus number of cycles





5//

T8T Characteristics

Figure 7. Non repetitive surge peak on-state current for a sinusoidal

Figure 8. Relative variation of gate trigger current and gate trigger voltage versus junction temperature

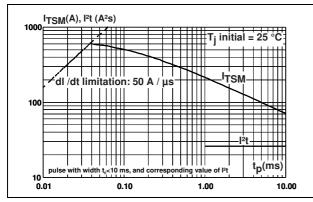
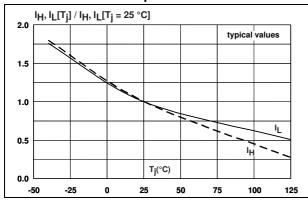


Figure 9. Relative variation of holding current and latching current versus junction temperature

Figure 10. Relative variation of static dV/dt immunity versus junction temperature



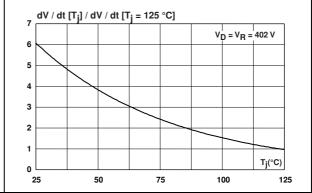
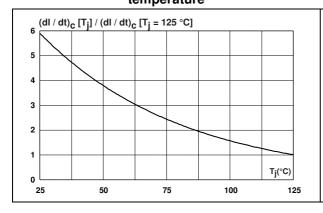
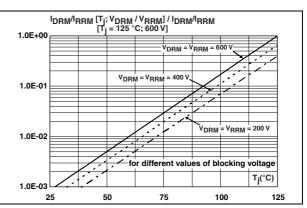


Figure 11. Relative variation of critical rate of decrease of main current versus junction temperature

Figure 12. Relative variation of leakage current versus junction temperature





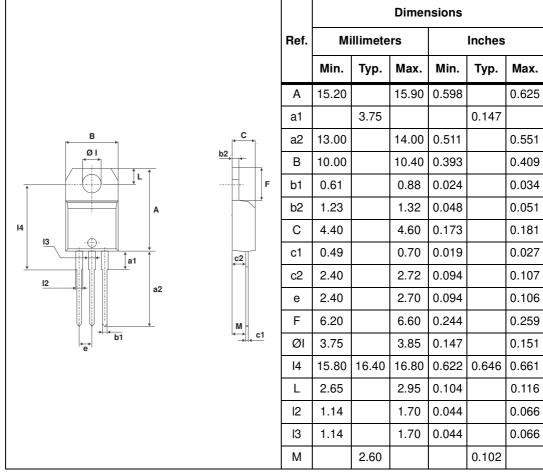
Package information T8T

2 Package information

- Epoxy meets UL94, V0
- Lead-free packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 6. TO-220AB Insulated dimensions





Ordering information

3 Ordering information

Figure 13. Ordering information scheme

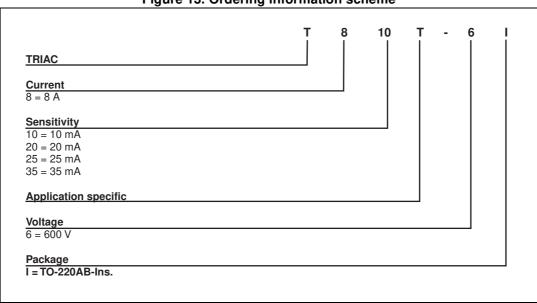


Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
T810T-6I	T810T-6I				
T820T-6I	T820T-6I	TO-220AB-Ins.	2.3 g	50	Tube
T825T-6I	T825T-6I	10-220AB-IIIS.	2.5 g	30	Tube
T835T-6I	T835T-6I				

4 Revision history

Table 8. Document revision history

Date	Revision	Changes
10-Sep-2009	1	First issue.
18-Jan-2010	2	Updated pag.1.
20-Sep-2011	3	Updated: Features. Replaced order codes with part numbers in Table 1.
16-Sep-2013	4	Replaced order codes with part numbers in Table 1.

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